

IN THE SPECIFICATION:

Please amend the first paragraph on page 2 as follows:

This application is a continuation of application Serial No. 09/004,214, filed January 9, 1998, now ~~US Patent No.~~ U.S. Patent 6,362,426 issued March 26, 2002.

Please amend the second paragraph on page 2 as follows:

Field of the Invention: The present invention relates generally to integrated circuit semiconductor chips. More particularly, ~~it~~ the present invention pertains to leadframes for bonding with the integrated circuits.

Please amend the fourth paragraph on page 2 as follows:

Two sources of noise in an integrated circuit package are switching noise and ~~crossecoupling~~ cross-coupling noise, or ~~crosstalk~~ cross-talk. Switching noise may be an inductive voltage spike that occurs on a conductive path as the result of rapid current switching in the conductive path. ~~Crosstalk~~ Cross-talk is the undesirable appearance of an electrical current in a conductive path as a result of mutual capacitance and inductance between the conductive path and other nearby conductive paths. At higher frequencies, the integrated circuit is even more susceptible to noise.

Please amend the first paragraph on page 3 as follows:

Another approach to reduce noise is to reduce the length of the transmission line on a leadframe by using diagonal leads. While diagonal leads minimize the length of the leads, the spacing between the leads would also be decreased. The decreased spacing would increase the overall ~~crosstalk~~ cross-talk between the leads, and would therefore be undesirable.

Please amend the second paragraph on page 3 as follows:

Accordingly, there is a need for an integrated circuit package in which the above benefits are achieved and the above problems are overcome.

Please amend the paragraph bridging pages 4 and 5 as follows:

A portion of a leadframe 200 is illustrated in Figure 2. The leadframe 200 has first and second sets of leads 210, 215. Although leads are discussed, other conductors can be used, such as lead fingers, and are considered within the scope of the invention. The first set of leads 210 extends from a first end 220 to a second end 230, and the second set of leads 215 extends from the first end 220 to a third end 225. For the first set of leads 210, the first end 220 is substantially perpendicular to the second end 230. For the first and second set of leads 210, 215, the first end 220 is for electrically coupling with an electronic system, such as a printed circuit board. The first end 220 can be coupled using reflow solder and other methods as known by those skilled in the art. The second end 230 of the first set of leads 210 and the third end 225 of the second set of leads 215 are adapted for coupling with a semiconductor die, as will be discussed further below.

Please amend the paragraph bridging pages 6 and 7 as follows:

An integrated circuit package including the leadframe according to the invention has reduced effective inductance and ~~crosstalk~~ cross-talk relative to existing integrated circuit packages. Below are simulated inductances and resistances for the tightly radiused leads of the conventional right angle leadframe shown in Figure 1 and the leads of the arcuate leadframe shown in Figure 2. The lead number refers to leads shown in figures 1 and 2. Like numbers in the figures indicate leads connecting between same locations on the die and same exterior connections.

Please amend the paragraph bridging pages 7 and 8 as follows:

Advantageously, the radiused leadframe provides for lower inductance, resistance, and capacitance of leads in a leadframe, as opposed to leads with tightly radiusd corners. These factors are important when the leads are carrying ~~high frequency~~ high-frequency signals, or signals having high-frequency harmonics, such as sub-nanosecond rise times. The continuous arcuate shape of the leads and the constant width of the leads maintains line spacing between the leads. This consistency maximizes layout space of the leadframe without increasing ~~crosstalk~~ cross-talk. In addition, a single leadframe strip or assembly can comprise leadframes for any number of a predetermined number of chips.